

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	215	(lead or tab or tape) adj frame and pad and test adj pad and (lead or wire) and (die or chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/09 09:37
L3	135	1 and wire adj bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/09 09:37
L4	83	3 and (overmould\$4 or overmold\$4 or encapsulat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/09 09:38
L5	37	4 and test\$4 and (burn adj in or "burn-in")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/09 09:38
L6	34	5 and solder adj (ball or sphere or preform)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/09 09:39
L7	36	5 and (cut or cutt\$4 or saw\$4 or dic\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/09 09:40
L8	33	6 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/09 09:40